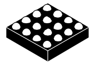
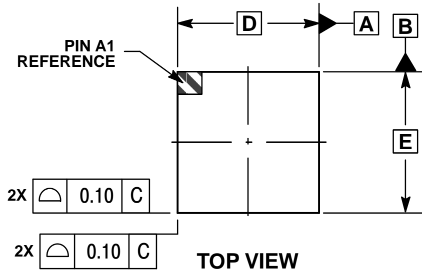
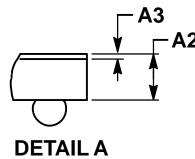


SCALE 4:1

WLCSP16, 1.56x1.56
CASE 567GF
ISSUE D

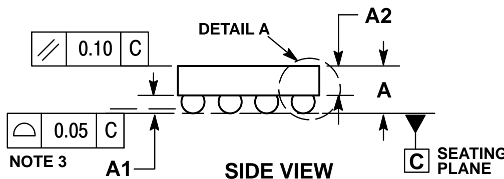
DATE 24 APR 2014

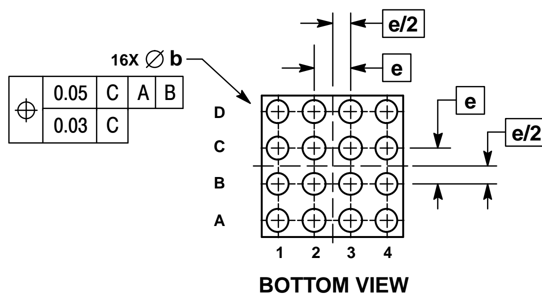




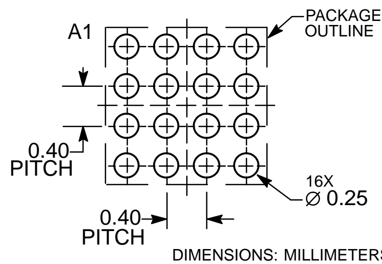
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS MIN	MILLIMETERS MAX
A	---	0.60
A1	0.17	0.23
A2	0.33	0.39
A3	0.04 BSC	
b	0.24	0.29
D	1.56 BSC	
E	1.56 BSC	
e	0.40 BSC	



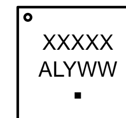


RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY M. HILTON.	15 NOV 2012
A	MOVED PIN ONE INDICATOR OF MARKING DIAGRAM FROM LOWER LEFT CORNER TO UPPER LEFT CORNER. REQ. BY M. HILTON.	11 DEC 2012
B	CORRECTED GENERIC MARKING DIAGRAM INFORMATION AND CHANGED DIMENSION A3 TO MIN AND MAX. REQ. BY M. HILTON.	07 JAN 2013
C	CORRECTED GENERIC MARKING DIAGRAM. REQ. BY M. HILTON.	10 APR 2014
D	CHANGED A3 DIMENSION FROM 0.02 MIN & 0.04 MAX TO 0.04 BSC. REQ. BY M. HILTON.	24 APR 2014

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